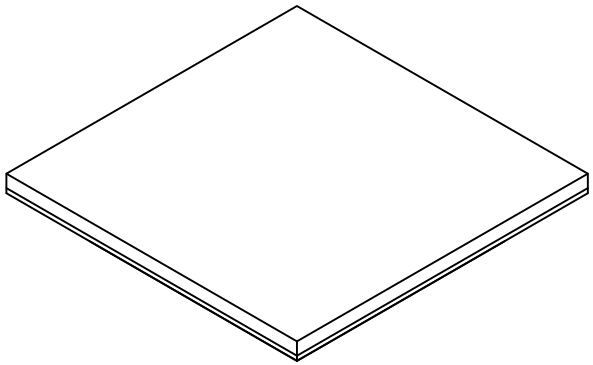
HMCCA,01/24/00,10:30:15,PBGAL2D101,M-01 SDEF0,01/12/01,11:09:26,MP617Q

REVISION HISTORY							
REV	ECN NUMBER	DESCRIPTION	ORIGINATOR	DATABASE FILE NAME	GERBER FILE NAME	INCORPORATOR	DATE
00	C06096	INITIAL RELEASE	MNOBL	N/A	N/A	MNOBL	05/06/99
01	C14076	ADDED 220 BALL COUNT	GREME	N/A	N/A	GREME	10/24/01



7. REFERENCE SPECIFICATIONS:
   A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
   B. AAWW SPEC #001-0519-2062: MARKING.

6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 256.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 16 X 16.

2. THE BASIC SOLDER BALL GRID PITCH IS 0.80mm.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
DECIMAL: X.X ±0.1, X.XX ±0.05, X.XXX ±0.030
ANGULAR ±1°
INTERPRET DIM AND TOL PER ASME Y14.5M - 1994
MATERIAL: N/A
FINISH: N/A
DO NOT SCALE DRAWING

THIRD ANGLE PROJECTION

APPROVALS	DATE
DESIGNED: MNOBL	04/14/99
CHECKED: JMICK	04/29/99
PRODUCT MANAGER: HBUEN	04/14/99
RELEASED: GSCHU	05/06/99

Amkor Technology, Inc. Chandler, Arizona, USA
Anam Semiconductor, Inc., Seoul, Korea
Amkor Technology Philippines, Inc. Manila, Philippines

TITLE: PACKAGE OUTLINE - THINMAF, 16 X 16 MATRIX, 14.00mm X 14.00mm X 1.10mm, 0.60mm MOLD CAP, 0.40mm BALL, 0.80mm PITCH, LAMINATE SUBSTRATE, AWW

SIZE	SID NUMBER	DWG NUMBER	REV
A3	N/A	75441	01

STRIP DWG NUMBER/REV	PKG OUTLINE DWG NO.	SCALE	SHEET
N/A	N/A	NONE	1 OF 3

FORM NO: MBFLAM1C1.DWG